Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D ***: Required Field**

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	2014-05-23
Contact Name *	Refer to " Supplier Comment" section	**Contact Title**	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	**Contact Email ***	Refer to " Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	**Representative Title**	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to " Supplier Comment" section	**Representative Email ***	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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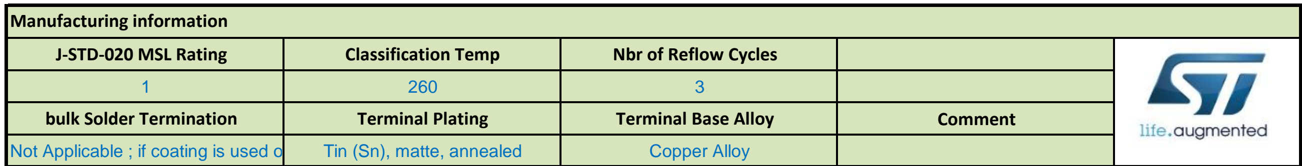
Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	AB6Y*F62J2AR	A	BO2A	2014-05-23
	Amount	UoM	Unit type	ST ECOPACK Grade
	50.00	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	3.75 - 4.3 - 0.98	2	J bend	
Comment	SMB Flat NEP: MD valid for CP: STTH1L06UFY.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	**true**
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th December 2013	
Query	**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**true**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						**Mfr Item Name**	**AB6Y*F62J2AR**					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
die (s)	Other inorganic materials	0.696	mg	supplier	die	Silicon (Si)	7440-21-3		0.663	mg	952586	13260
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.02	mg	28736	400
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.005	mg	7184	100
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.002	mg	2874	40
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	1437	20
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.005	mg	7184	100
Leadframe	Copper & its alloys	19.19	mg	supplier	alloy	Copper (Cu)	7440-50-8		19.165	mg	998697	383300
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.009	mg	469	180
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.016	mg	834	320
Soft solder	Solder	0.406	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	0.388	mg	955665	7760
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.01	mg	24631	200
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.008	mg	19704	160
Bonding wire	Other inorganic materials	0.145	mg	supplier	wire	Copper (Cu)	7440-50-8		0.145	mg	1000000	2900
encapsulation	Other Organic Materials	28.833	mg	supplier	mold compound	Silica, vitreous	60676-86-0		25.23	mg	875039	504600
encapsulation				supplier	mold compound	Epoxy Resin	85954-11-6		1.153	mg	39989	23060
encapsulation				supplier	mold compound	Epoxy resin	Proprietary		1.153	mg	39989	23060
encapsulation				supplier	mold compound	Phenol Resin	26834-02-6		1.153	mg	39989	23060
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.144	mg	4994	2880
connections coating	Solder	0.73	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.73	mg	1000000	14600